



100% Material Declaration Data Sheet CP56

PK146 (v1.2) September 28, 2006

Material Declaration Data Sheet

Average Weight: 0.1 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.00215	2.15%
	Silicon	7440-21-3	100.00		0.00215	
Die Attach Material					0.0005	0.50%
	Silver	7440-22-4	78.00		0.00039	
	Resin	Trade Secret	22.00		0.00011	
Encapsulant					0.03956	39.56%
	Epoxy Resin	Trade Secret	6.00		0.0023736	
	Phenolic Resin	Trade Secret	6.00		0.0023736	
	Carbon Black	1333-86-4	0.50			
	Bismuth	7440-69-9	Max 1.00		0.0003956	
	SiO2 Filler	60676-86-0	86.50		0.0342194	
Laminate					0.0126	12.60%
	Bismaleimide / Triazine Board	13676-54-5 / 25722-66-1	72.285		0.00910791	
	Copper	7440-50-8	9.780	Metal Layer	0.00123228	
	Nickel	7440-02-0	7.890	Metal Layer	0.00099414	
	Gold	7440-57-5	1.140	Metal Layer	0.00014364	
	Antimony Pentoxide	1314-60-9	0.005	Flame Retardant	0.00000063	
	Brominated Resin	68541-56-0	8.90	Flame Retardant	0.0011214	
Bond Wire					0.00023	0.23%
	Gold	7440-57-5	100.00		0.00023	
Solder Balls					0.04496	44.96%
	Tin	7440-31-5	63.00		0.0283248	
	Lead	7439-92-1	37.00		0.0166352	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
4/06/06	1.0	Initial release.
7/21/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.